

Abstract of the Disclosure

A compression bonding method includes patterning a metal bonding film in predetermined shapes on a substrate; and disposing a bonded element above the metal bonding film and applying heat to the substrate and pressure to the bonded element, thereby bonding the bonded element to the substrate having the metal bonding film. Since the compression bonding method allows bonded elements having various shapes and sizes to be bonded to a substrate at a low temperature and pressure, manufacturing is simplified, and the compression bonding method can be applied to various sealing and packaging processes.

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